

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/14/2022

Details for "LM358PWRG4-JF"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LM358PWRG4-JF	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	PW 8	3x4.4x1.0	34.2

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.033113	100	1000000	0.096857	969
Sub-Total			0.033113	100	1000000	0.096857	969
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.141539	79.999887	799999	0.414007	4140
Thermoplastics	Epoxy	85954-11-6	0.035385	20.000113	200001	0.103503	1035
Sub-Total			0.176924	100	1000000	0.51751	5175
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	12.6633	97.41	974100	37.040668	370407
Copper and Its Alloys	Iron	7439-89-6	0.312	2.4	24000	0.912613	9126
Copper and Its Alloys	Phosphorus	7723-14-0	0.0039	0.03	300	0.011408	114
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.0039	0.03	300	0.011408	114
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.0039	0.03	300	0.011408	114
Zinc and Its Alloys	Zinc	7440-66-6	0.013	0.1	1000	0.038026	380
Sub-Total			13	100	1000000	38.02553	380255
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.247312	95.12	951200	0.723398	7234
Precious Metals	Gold	7440-57-5	0.002028	0.78	7800	0.005932	59
Precious Metals	Palladium	7440-05-3	0.01066	4.1	41000	0.031181	312
Sub-Total			0.26	100	1000000	0.760511	7605
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	17.31909	86.000003	860000	50.659044	506590
Other Plastics and Rubber	Carbon Black	1333-86-4	0.060415	0.299998	3000	0.176716	1767
Thermoplastics	Epoxy	85954-11-6	2.758971	13.699999	137000	8.070103	80701
Sub-Total			20.138476	100	1000000	58.905863	589059
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.579045	100	1000000	1.69373	16937
Sub-Total			0.579045	100	1000000	1.69373	16937
Total			34.187558			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.